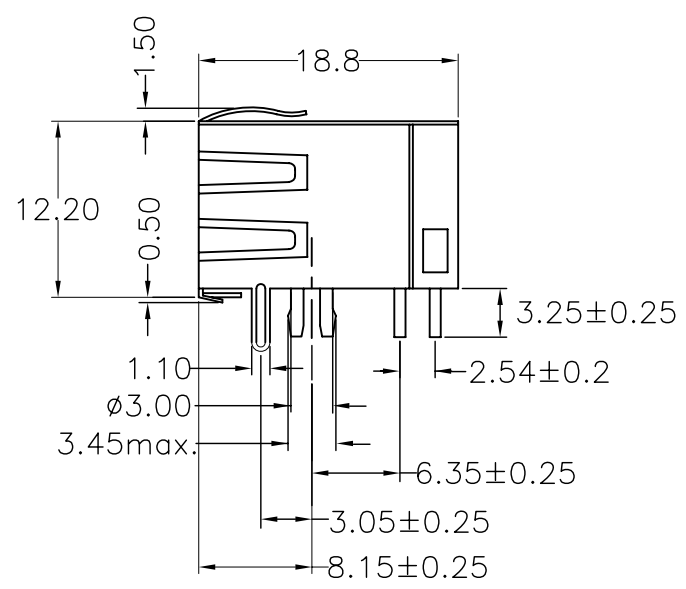
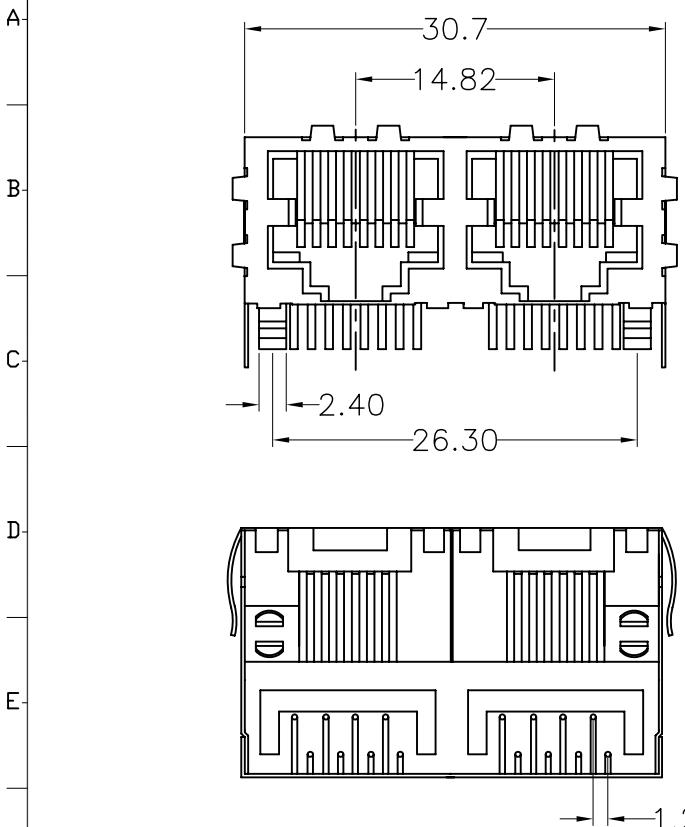


REV.	SPECIFICATION	ECN NO.	APPD.



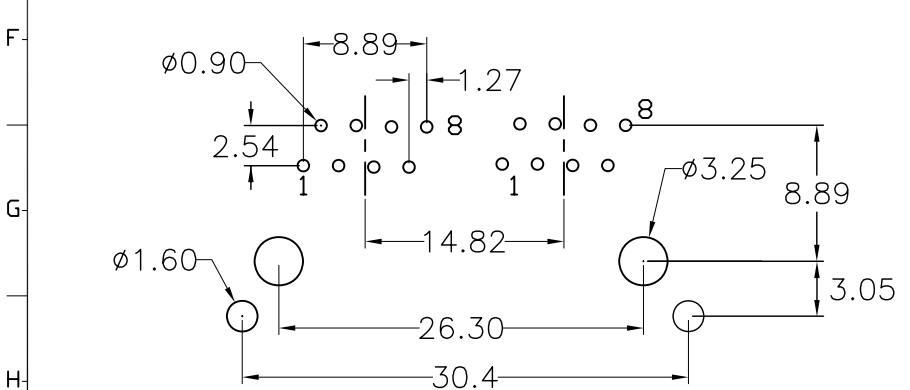
**Material:**

Housing: Termoplastic Poyester Glass Filled UL94V-0.  
 Contacts: Copper Alloy.  
 Shell: Copper Alloy.

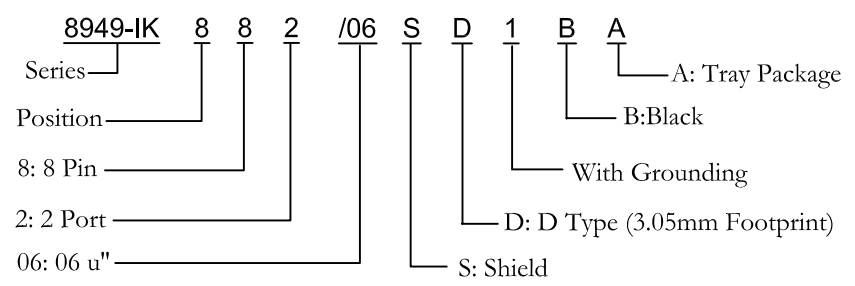
**Electrical Characteristics:**

Current Rating: 1.5 AMP.  
 Insulator Resistance: 500MΩmin. at DC 500V.  
 Contact Resistance: 40mΩmax. at DC 100mA.  
 Operating Temperature: -40°C ~ +85°C.

**\*RoHS Compliant**



P.C.Board Layout



Tolerances	Dwg. No.	8949D02131	Title:
x = ±0.50	Projection		8949-IK Series Modular Jack
.x = ±0.25	Unit	mm	
.xx = ±0.15	Scale	1:1	
	Drawn By	Peggy09/17'13	①563

Title:			
8949-IK Series Modular Jack			
①563			

<b>OUPIN</b>			
OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 8949-IK882/06SD1BA			
SHEET	1/1	Ver.No.	A2